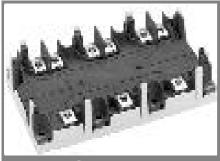
## **SKiM 380GD176DM ...**



SKiM 5®

## Trench IGBT Modules

#### **SKiM 380GD176DM**

**Target Data** 

#### **Features**

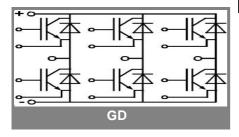
- · Homogeneous Si
- Trench = Trenchgate Technology
- V<sub>CEsat</sub> with positive temperature coefficient
- High short circuit capability, limiting to 6x I<sub>C</sub>

### **Typical Applications**

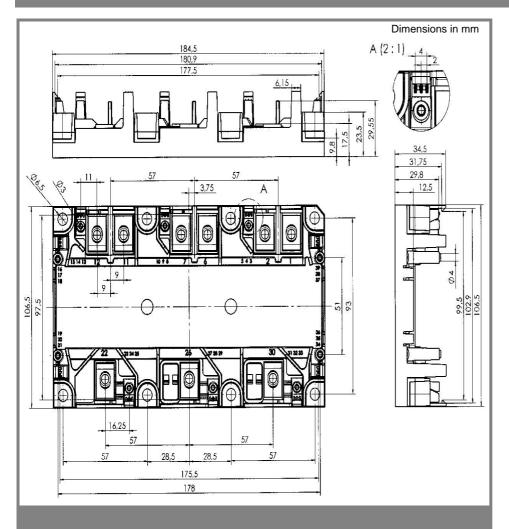
- AC inverter drives mains 575 -750 V AC
- public transport (auxiliary syst.)

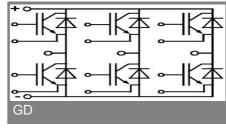
Absolute Maximum Ratings		T <sub>case</sub> = 25°C, unless otherwise specified							
Symbol	Conditions	Values	Units						
IGBT									
$V_{CES}$		1700	V						
V <sub>CES</sub>	T <sub>h</sub> = 25 (70) °C	425 (325)	Α						
I <sub>CM</sub>	$T_h = 25 (70)  ^{\circ}C, t_p = 1  \text{ms}$	850 (650)	Α						
$V_{GES}$	·	± 20	V						
$T_j(T_{stg})$	$T_{OPERATION} \leq T_{stg}$	-40 125	°C						
$V_{isol}$	AC, 1 min.	4000	V						
Inverse diode									
$I_F = -I_C$	T <sub>h</sub> = 25 (70) °C	380 (285)	Α						
$I_{FM} = -I_{CM}$	$T_h = {^{\circ}C}, t_p < ms$	850 (650)	Α						
I <sub>FSM</sub>	$t_p = 10 \text{ ms; sin.; } T_j = 150 ^{\circ}\text{C}$	3300	Α						

<b>Characteristics</b> T <sub>case</sub> = 25°C, unless otherwise spe					
Symbol	Conditions	min.	typ.	max.	Units
IGBT					•
$V_{GE(th)}$	$V_{GE} = V_{CE}$ ; $I_C = 18 \text{ mA}$	5,2	5,8	6,4	V
I <sub>CES</sub>	$V_{GE} = 0; V_{CE} = V_{CES};$ $T_i = 25 °C$			3	mA
$V_{CEO}$	$V_{GF} = V; T_i = {^{\circ}C}$			1,2 (1,1)	V
r <sub>CE</sub>	$V_{GE} = V; T_i = {^{\circ}C}$			3,3 (4,8)	mΩ
V <sub>CEsat</sub>	I <sub>C</sub> = 375 A; V <sub>GE</sub> = 15 V,	1,6	2 (2,4)	2,45	V
OLSAI	T <sub>i</sub> = 25 (125) °C on chip level				
C <sub>ies</sub>	V <sub>GF</sub> = 0; V <sub>CF</sub> = 25 V; f = 1 MHz		33		nF
Coes	V <sub>GE</sub> = 0; V <sub>CE</sub> = 25 V; f = 1 MHz		1,4		nF
C <sub>res</sub>	$V_{GE} = 0; V_{CE} = 25 V; f = 1 MHz$		1,1		nF
L <sub>CE</sub>	$T_c = 25 ^{\circ}C$			20	nΗ
R <sub>CC'+EE'</sub>			0,9 (1,1)		$m\Omega$
t <sub>d(on)</sub>	V <sub>CC</sub> = 1200 V				ns
t <sub>r</sub> `´	I <sub>C</sub> = 375 A				ns
$t_{d(off)}$	$R_{Gon} = R_{Goff} = 3 \Omega$				ns
t <sub>f</sub>	T <sub>j</sub> = 125 °C				ns
$E_{on}\left(E_{off}\right)$	V <sub>GE</sub> ± 15 V		225 (150)		mJ
Inverse d					
$V_F = V_{EC}$	I <sub>F</sub> = 375 A; V <sub>GE</sub> = 0 V; T <sub>i</sub> = 25 (125) °C				V
$V_{TO}$	$T_i = 25 (125) \text{ C}$ $T_i = 25 (125) \text{ °C}$				V
r <sub>T</sub>	$T_i = 25 (125) ^{\circ} C$				V
I <sub>RRM</sub>	$I_F = 375 \text{ A}; T_i = 25 ^{\circ}\text{C}$				Ā
Q <sub>rr</sub>	$V_{GF} = 0 \text{ V di/dt} = A/\mu s$				μC
E <sub>rr</sub>	R <sub>Gon</sub> = R <sub>Goff</sub> =				mJ
	characteristics				
R <sub>thjh</sub>	per IGBT	1		0,09	K/W
R <sub>thjh</sub>	per FWD			0,14	K/W
	ture Sensor	1			1
R <sub>TS</sub>	T = 25 (125) °C	1	1 (1,67)		kΩ
tolerance	T = 25 (125) °C		3 (2)		%
Mechanic	cal data	1			1
M <sub>1</sub>	to heatsink (M5)	2		3	Nm
$M_2$	for terminals (M6)	4		5	Nm



# SKiM 380GD176DM ...





This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.